



Material Content Data Sheet



Halogen-Free

Sales Product Name	IAUZ40N10S5N130	Issued	11. May 2021
MA#	MA005406777		
Package	PG-TSDSON-8-32	Weight*	35.61 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.549	1.54	1.54	15411	15411
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		87	
	non noble metal	zinc	7440-66-6	0.012	0.03		349	
	non noble metal	iron	7439-89-6	0.249	0.70		6987	
	non noble metal	copper	7440-50-8	10.102	28.37	29.11	283710	291133
wire	noble metal	gold	7440-57-5	0.028	0.08	0.08	782	782
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1033	
	plastics	epoxy resin	-	1.894	5.32		53188	
	inorganic material	silicondioxide	60676-86-0	16.456	46.23	51.65	462163	516384
leadfinish	non noble metal	tin	7440-31-5	0.400	1.12	1.12	11241	11241
plating	noble metal	silver	7440-22-4	0.086	0.24	0.24	2405	2405
solder	non noble metal	tin	7440-31-5	0.016	0.04		449	
	noble metal	silver	7440-22-4	0.020	0.06		561	
	non noble metal	lead	7439-92-1	0.763	2.14	2.24	21425	22435
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			26	
	non noble metal	zinc	7440-66-6	0.004	0.01		102	
	non noble metal	iron	7439-89-6	0.073	0.20		2046	
	non noble metal	copper	7440-50-8	2.958	8.31	8.52	83060	85234
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			16	
	non noble metal	zinc	7440-66-6	0.002	0.01		66	
	non noble metal	iron	7439-89-6	0.047	0.13		1319	
	non noble metal	copper	7440-50-8	1.908	5.36	5.50	53574	54975
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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